

Features

- Fast switching speed.
- Very low leakage current
- Low capacitance
- Surface mount package Ideally Suited for Automatic insertion

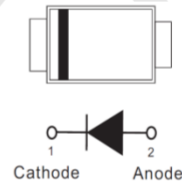
APPLICATIONS

- Case: SOD-323 Package
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.00014 ounces, 0.0041 grams

SOD323



PIN	DESCRIPTION
1	Cathode
2	Anode



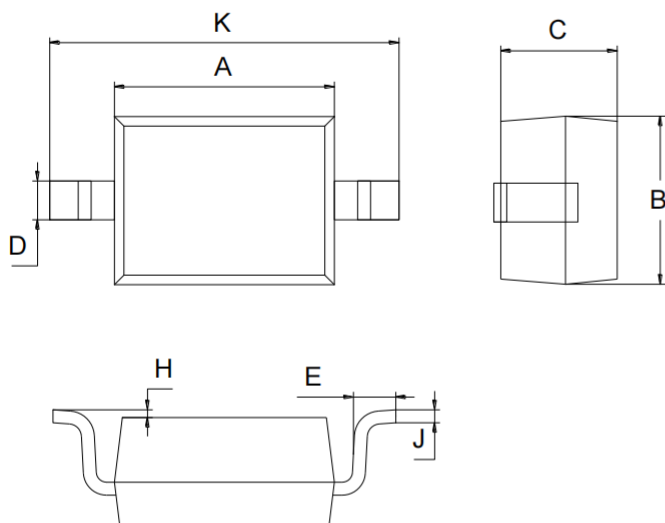
Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS
Reverse Voltage		V_R	100	V
Peak Reverse Voltage		V_{RM}	100	V
Maximum Average Forward Current		$I_{F(AV)}$	200	mA
Non-repetitive Peak forward current at $T_J(\text{init})=25^\circ\text{C}$	tp = 0.001 ms	I_{FSM}	4	A
	tp = 1 ms		1	
	tp = 1 s		0.5	
Repetitive peak forward current tp $\leq$ 0.5 ms ; D $\leq$ 0.25		I_{FRM}	500	mA
Power Dissipation		$P_D^{(1)}$	400	mW
Maximum Junction Capacitance Measured at 1 MHZ And Applied $V_R = 0$ V		C_J	1.5	pF
Typical Thermal Resistance		$R_{\theta JA}^{(2)}$	500	$^\circ\text{C/W}$
		$R_{\theta JC}^{(1)}$	200	
Operating Junction Temperature Range		T_J	-55~150	$^\circ\text{C}$
Storage Temperature Range		T_{STG}	-55~150	$^\circ\text{C}$

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Forward Voltage	V_F	$I_F = 1 \text{ mA}, T_J = 25^\circ\text{C}$	-	-	0.715	V
		$I_F = 10 \text{ mA}, T_J = 25^\circ\text{C}$	-	-	0.855	
		$I_F = 50 \text{ mA}, T_J = 25^\circ\text{C}$	-	-	1	
		$I_F = 150 \text{ mA}, T_J = 25^\circ\text{C}$	-	-	1.25	
Reverse Current	I_R	$V_R = 25 \text{ V}, T_J = 25^\circ\text{C}$	-	-	0.03	μA
		$V_R = 100 \text{ V}, T_J = 25^\circ\text{C}$	-	-	0.5	
Maximum Reverse Recovery Time	$T_{RR}^{(3)}$	---	-	-	4	ns

Outline Drawing - SOD323 (unit: mm)



SOD-323		
Dimension	Min.	Max.
A	1.60	1.80
B	1.20	1.40
C	0.80	0.90
D	0.25	0.35
E	0.22	0.42
H	0.02	0.10
J	0.05	0.15
K	2.55	2.75

Mounting Pad Layout-SOD323 (unit: mm)

